Please amend the present application as follows:

Claims

The following is a copy of Applicant's claims that identifies language being added with underlining ("___") and language being deleted with strikethrough ("~~—~~"), as is applicable:

1-21. (Canceled)

22. (Currently amended) A fluid ejection device comprising:

a heating element on a substrate surface; and

a cover layer on the substrate surface, the cover layer defining a firing chamber formed about the heating element and defining a nozzle over the firing chamber, wherein the cover layer includes a primer layer, a chamber layer, a nozzle layer, a photon barrier layer between the nozzle layer and the chamber layer that at least partially defines the nozzle, and a top coat layer, wherein at least one of the layers includes a dry film.

23. (Previously Presented) The fluid ejection device of claim 22 wherein the primer layer and the chamber layer at least partially define the firing chamber.

24. (Previously Presented) The fluid ejection device of claim 22 wherein the nozzle layer at least partially defines the nozzle.

25. (Canceled)

26. (Previously Presented) The fluid ejection device of claim 22 wherein the primer layer, the chamber layer, and the nozzle layer include dry film.

27. (Previously Presented) The fluid ejection device of claim 22 wherein the cover layer includes at least two SU8 layers.

28. (Previously Presented) A fluid ejection device comprising:

a resistor on a substrate surface;

a first polymer layer formed over the substrate surface and surrounding the resistor;

a second polymer layer formed over the first polymer layer and defining a nozzle; and

a top coat layer defining a countersunk bore corresponding to the nozzle.

29. (Previously Presented) The fluid ejection device of claim 28 wherein at least one of the first and second polymer layers comprises SU8.

30. (Previously Presented) The fluid ejection device of claim 28 wherein one of the first and second polymer layers includes a dry film.

31-33. (Canceled)

34. (Previously Presented) A fluid ejection device comprising:

a resistor on a substrate surface; and

a first polymer layer defining a firing chamber formed over the resistor;

a second polymer layer defining a nozzle over the firing chamber, and

a top coat layer defining a countersunk bore associated with the nozzle,

wherein at least one of the first and second layers includes a dry film.

35. (Previously Presented) The fluid ejection device of claim 34 further comprising a third layer between the first and second layers, wherein the third layer at least partially defines the firing chamber.

36. (Previously Presented) The fluid ejection device of claim 35 wherein the first, second and third layers include dry film.

37. (Previously Presented) The fluid ejection device of claim 35 wherein the first and second layers are SU8 layers.

38-42. (Canceled)

43. (Previously Presented) The fluid ejection device of claim 22 wherein at least one outer edge of the chamber layer is offset from a respective outer edge of the primer layer to expose a surface of the primer layer.

44. (Previously Presented) The fluid ejection device of claim 28 further comprising a primer layer formed between the substrate surface and the first polymer layer.

45. (Previously Presented) The fluid ejection device of claim 44 wherein at least one edge of the first polymer layer is offset from a respective outer edge of the primer layer to expose a surface of the primer layer.

46. (Canceled)